



Material Content Data Sheet



Sales Product Name	BTS50055-1TMA	Issued	17. February 2022
MA#	MA005698523		
Package	PG-TO220-7-4	Weight*	1532.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	13.394	0.87	0.87	8740	8740
chip_2	inorganic material	silicon	7440-21-3	2.120	0.14	0.14	1383	1383
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		157	
	non noble metal	iron	7439-89-6	0.804	0.05		525	
	non noble metal	copper	7440-50-8	802.842	52.40	52.47	523897	524579
wire	non noble metal	aluminium	7429-90-5	6.616	0.43	0.43	4318	4318
encapsulation	inorganic material	zincoxide	1314-13-2	5.794	0.38		3781	
	miscellaneous	miscellaneous	-	23.174	1.51		15123	
	plastics	epoxy resin	-	86.904	5.67		56709	
	inorganic material	silicondioxide	60676-86-0	463.487	30.25	37.81	302451	378064
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7890	7890
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	141	142
solder	non noble metal	tin	7440-31-5	0.164	0.01		107	
	noble metal	silver	7440-22-4	0.205	0.01		134	
	non noble metal	lead	7439-92-1	7.820	0.51	0.53	5103	5344
glue	plastics	Polyimide	26023-21-2	0.217	0.01	0.01	142	142
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69308	69398
*deviation	< 10%					Sum in total:	100.00	
								1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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